

Customer No.: 31561
Docket No.: 11053-US-PA-1
Application No.: 10/707,457

AMENDMENTS

In The Claims:

Claims 1-10 (cancelled).

11. (currently amended) A discrete semiconductor circuit component comprising a circuit die, said circuit die having at least ~~one~~ two electrical contact areas for connection to the packaging of said semiconductor circuit component, said at least one electrical contact areas being bond to the corresponding lead of said packaging by metallic material formed by a metal ball of prescribed feed melted during the fabrication of said component, wherein said at least one electrical contact areas are disposed on the two opposite surfaces of said circuit die.

12. (previously amended) The discrete semiconductor circuit component of claim 11, wherein said metal ball contains copper.

13. (previously amended) The discrete semiconductor circuit component of claim 11 wherein said metal ball contains aluminum.

14. (previously amended) The discrete semiconductor circuit component of claim 11, wherein said metal ball contains tin.

15. (previously amended) The discrete semiconductor circuit component of claim 11, wherein said metal ball contains lead.

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16. (previously amended) The discrete semiconductor circuit component of claim 11, further comprising a second metal bump.

17. (previously amended) The discrete semiconductor circuit component of claim 16, wherein said two metal bumps being of different sizes.

18. (previously amended) The discrete semiconductor circuit component of claim 16, wherein said two metal bumps being of different shapes.

19. (previously amended) The discrete semiconductor circuit component of claim 16, wherein said two metal bumps being made of different materials.

20. (previously amended) The discrete semiconductor circuit component of claim 11, further comprising at least one more metal bump.